Errata MSPM0C1103, MSPM0C1104, MSPS003F3, MSPS003F4 Microcontrollers



ABSTRACT

This document describes the known exceptions to the functional specifications (advisories).

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1 Functional Advisories

Advisories that affect the device operation, function, or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
ADC_ERR_06	1
I2C_ERR_03	1
PMCU_ERR_07	1

2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

✓ The check mark indicates that the issue is present in the specified revision.

3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

5 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

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XMS – Experimental device that is not necessarily representative of the final device electrical specifications

MSP - Fully qualified production device

Support tool naming prefixes:

X: Development-support product that has not yet completed Texas Instruments internal qualification testing.

null: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

5.1 Device Symbolization and Revision Identification

The package diagrams below indicate the package symbolization scheme, and Table 5-1 defines the device revision to version ID mapping.



 YM = Year, month date code
 # = Die revision

 S = Assembly site
 LLLL = Assembly lot code

Figure 5-1. Package Symbolization

Table 5-1. Die Revisions

Revision Letter (package marking)	Version (in the device factory constants memory)
В	2

The revision letter indicates the product hardware revision. Advisories in this document are marked as applicable or not applicable for a given device based on the revision letter. This letter maps to an integer stored in the memory of the device, which can be used to look up the revision using application software or a connected debug probe.

6 Advisory Descriptions

ADC_ERR_06	DC offset error needs to be calibrated in application code	
Revisions Affected	Rev C	
Details	The calibration data of ADC offset error is not applied correctly AND needs to be implemented in application code.	
Workaround	The calibration data is stored at address 0x41C40040 in factory region. Two DriverLib APIs DL_ADC12_getADCOffsetCalibration AND DL_FactoryRegion_getADCOffset have been implemented in the SDK to facilitate this.	
	STATIC_INLINE int16_t DL_ADC12_getADCOffsetCalibration(float userRef)	
	{	
	float adcBuff = DL_FactoryRegion_getADCOffset() * (3.3 / userRef);	
	return (int16_t)(round(adcBuff));	
	}	
	STATIC_INLINE float DL_FactoryRegion_getADCOffset(void)	
	{	
	return ((float) (*(int16_t *) (0x41C40040)));	
	}	
	The calibration data can be saved into a variable AND subsequently applied to the ADC conversion result.	
	Below is the example code demonstrating how to apply the calibration data, which has been integrated into the ADC examples provided in the SDK:	
	volatile uint16_t gAdcResult;	
	volatile int16_t gADCOffset;	
	gADCOffset = DL_ADC12_getADCOffsetCalibration(ADC12_0_ADCMEM_0_REF_VOLTAGE_V);	
	gAdcResult = DL_ADC12_getMemResult(ADC12_0_INST, DL_ADC12_MEM_IDX_0);	
	int16_t adcRaw = (int16_t) gAdcResult + gADCOffset;	
	if (adcRaw < 0) {	
	adcRaw = 0;	
	}	
	if (adcRaw > 4095) {	
	adcRaw = 4095;	
	}	
	gAdcResult = (uint16_t) adcRaw;	
	The ADC offset calibration data can be applied for the example use cases below:	

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ADC_ERR_06 (continued)	ADC offset error needs to be calibrated in application code		
	 Utilizing ADC without DMA - the offset needs to be added to ADC result from the register MEMRES. Utilizing ADC with DMA - the offset needs to be added to ADC result stored in the memory address. Utilizing ADC window comparator - the offset needs to be subtracted from window threshold used when configuring the comparator feature. 		
I2C_ERR_03	I2C peripheral mode cannot wake up device when sourced from MFCLK		
Revisions Affected	Rev C		
Details	IF I2C module is configured in peripheral mode AND I2C is clocked from MFCLK (Middle Frequency Clock) AND device is placed in STOP2 or STANDBY0/1 power modes, THEN I2C fails to wakeup the device when receiving data.		
Workaround	Set I2C to be clocked by BUSCLK instead of MFCLK, if needing low power wakeup upon receiving data in I2C peripheral mode.		
PMCU_ERR_07	The LFOSCGOOD bit in the CLKSTATUS register does not indicate the correct LFOSC status		
Revisions Affected	Rev C		
Details	When LFOSC startup has completed, the LFOSCGOOD bit has not been asserted by the LFOSC startup monitor.		
Workaround	Avoid using the LFOSCGOOD bit to check if the LFOSC is ready or not.		

7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	Changes from Revision * (October 2023) to Revision A (May 2024)	Page
•	Removed ADC_ERR_04, ADC_ERR_05, PMCU_ERR_04, PMCU_ERR_05, PMCU_ERR_06, and	
	UART_ERR_01; Added ADC_ERR_06, I2C_ERR_03, and PMCU_ERR_07	1

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